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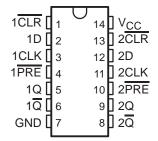
 Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

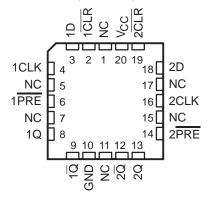
The 'HC74 contain two independent D-type positive-edge-triggered flip-flops. A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of CLK. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

The SN54HC74 is characterized for operation over the full military temperature range –55°C to 125°C. The SN74HC74 is characterized for operation from –40°C to 85°C.

SN54HC74...J OR W PACKAGE SN74HC74...D, DB, N, OR PW PACKAGE (TOP VIEW)



SN54HC74...FK PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE

	INP	UTS		OUTI	PUTS
PRE	CLR	CLK	D	Q	Q
L	Н	Х	Х	Н	L
Н	L	X	Χ	L	Н
L	L	X	Χ	н†	H [†]
Н	Н	\uparrow	Н	Н	L
Н	Н	\uparrow	L	L	Н
Н	Н	L	Х	Q_0	\overline{Q}_0

[†]This configuration is unstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

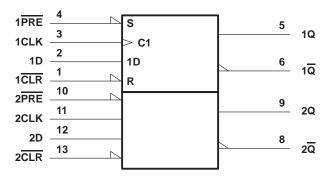


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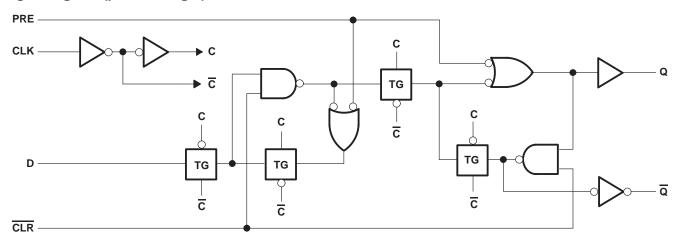
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logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range‡

Supply voltage range, V _{CC}		0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	ee Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CO}$	c) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	- 	±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ _{JA} (see Note 2):	: D package	127°C/W
	DB package	158°C/W
	N package	78°C/W
	PW package	170°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

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recommended operating conditions

			S	N54HC7	4	SN74HC74			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vсс	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
ViH	V _{IH} High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
	Low-level input voltage	V _{CC} = 2 V	0		0.5	0		0.5	V
V_{IL}		V _{CC} = 4.5 V	0		1.35	0		1.35	
		VCC = 6 V	0		1.8	0		1.8	
٧ _I	Input voltage		0		VCC	0		VCC	V
Vo	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V	0		1000	0		1000	
t _t	Input transition (rise and fall) time	$V_{CC} = 4.5 \text{ V}$	0		500	0		500	ns
		V _{CC} = 6 V	0		400	0		400	
TA	Operating free-air temperature		-55		125	-40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		Vaa	T _A = 25°C			SN54HC74		SN74HC74		UNIT
PARAMETER	1251 00	CNDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
			2 V	1.9	1.998		1.9		1.9		
	I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4			
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
		I _{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	
			4.5 V		0.001	0.1		0.1		0.1	
VOL	$V_I = V_{IH} \text{ or } V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	1
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0	·	6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			4		80		40	μΑ
C _i			2 V to 6 V		3	10		10		10	pF

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			V	T _A =	25°C	SN54	HC74	SN74I	HC74	UNIT	
			Vcc	MIN	MAX	MIN	MAX	MIN	MAX	ONT	
	f _{clock} Clock frequency		2 V	0	6	0	4.2	0	5		
fclock			Clock frequency	4.5 V	0	31	0	21	0	25	MHz
			6 V	0	36	0	25	0	29		
t _W Pulse duration		2 V	100		150		125				
	PRE or CLR low	4.5 V	20		30		25				
		6 V	17		25		21				
	Pulse duration		2 V	80		120		100		ns	
		CLK high or low	4.5 V	16		24		20			
			6 V	14		20		17			
			2 V	100		150		125		ns	
		Data	4.5 V	20		30		25			
۱.	Setup time before CLK↑		6 V	17		25		21			
t _{su}	Setup time before CLK		2 V	25		40		30			
		PRE or CLR inactive	4.5 V	5		8		6			
			6 V	4		7		5		1 1	
			2 V	0		0		0			
th	Hold time, data after CLK↑		4.5 V	0		0		0		ns	
			6 V	0		0		0			

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

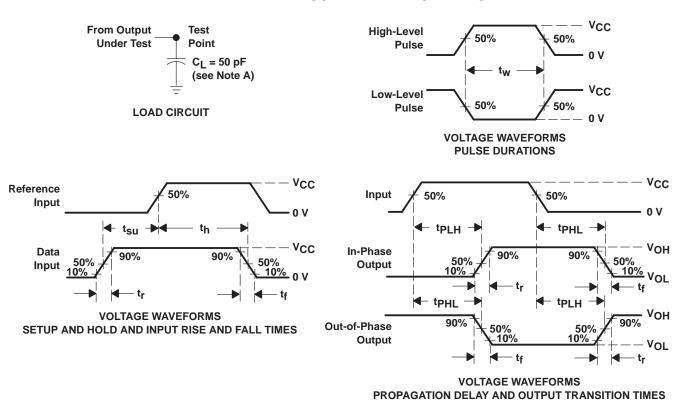
DADAMETED	FROM TO		Vaa	T,	λ = 25°C	;	SN54l	HC74	SN74l	1C74	UNIT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	10		4.2		5		
f _{max}			4.5 V	31	50		21		25		MHz
			6 V	36	60		25		29		
		Q or $\overline{\mathbb{Q}}$	2 V		70	230		345		290	ns
	PRE or CLR		4.5 V		20	46		69		58	
			6 V		15	39		59		49	
^t pd			2 V		70	175		250		220	115
	CLK	Q or \overline{Q}	4.5 V		20	35		50		44	
			6 V		15	30		42		37	
			2 V		28	75		110		95	
t _t		Q or \overline{Q}	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per flip-flop	No load	35	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.
- C. For clock inputs, $f_{\mbox{max}}$ is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

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